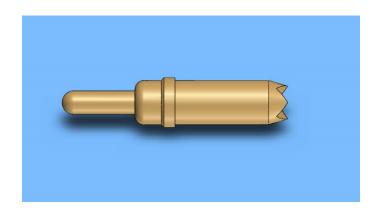


E5544 FEATURES

- <-1db insertion loss to >40 GHz
- <2:1 VSWR to >40 GHz
- 30g operating spring force
- $Z0 = 43.8\Omega$
- <31.5 ps risetime
- 30 milliohms
- 2.7 Amps max drive current



GENERAL DESCRIPTION

The E5544 series spring probes from Signal Integrity Inc. are designed to meet the rigorous test probe bandwidth of the wireless and RF test markets as well as very fast rise times in test applications for telecommunication and broadband data communications system-on-a-chip devices. The risetime requirements for these devices are usually well below 32 picoseconds. Along with speed and accuracy, these probes are designed for testing very fine pitch to 1.0mm, well suited to the packaging constraints driven by the consumer wireless market.

The high bandwidth of these probes provides very low insertion loss up to >40GHz. These probes will provide transparent operation on Bluetooth, 802.11b and 3G wireless protocol devices as well as exceed the test probe demands of proprietary microwave communications devices and systems.

With an impulse risetime of less than 31.5ps and a propagation delay of 15.5ps, the AC performance of the E5544 probe is transparent for test applications and interconnections solutions that operate in high speed CMOS, SiGe and GaAs technologies.

SERIES E5544 MODELS: ORDERING INFORMATION

	E Series 1.0mm (.0394inch) Pitch						
Model	Length Operating / Initial inches [mm]	DUT Plunger and Plating	Spring	Operating Spring Force			
E5544-B2	.098 [2.49] / .124 [3.15]	4 Point Crown – Gold	Stainless Steel	30 Grams			



FUNCTIONAL SPECIFICATIONS

Model	E5544-B2					
	Corner	Edge	Field	Units		
TDT Risetime thru 50Ω	31.5	30	30	ps		
TDR Risetime open circuit	31.5	30	31.5	ps		
TDR Risetime short circuit	51	30	27	ps		
Signal Delay into 50Ω	17.2	16.0	15.5	ps		
Insertion Loss <-1db	14.9	>40	>40	GHz		
Insertion Loss <-3db	38.7	>40	>40	GHz		
VSWR <2:1	>40	>40	>40	GHz		
Equivalent Circuit	Paramete	ers	1			
	Min.	Тур.	Max.	Units		
Pin Inductance		0.70		nН		
Pin Capacitance to ground		0.362		pF		
Mutual Inductance		0.030		nН		
Mutual Capacitance		0.181		pF		
Transmission Line						
Zo] [43.8		Ω		
T1		15.5		ps		

MAXIMUM DC CURRENT							
DUTY CYCLE DC 50% 25% 10% 1%							
AMPS	2.74	2.93	3.90	4.78	5.76		

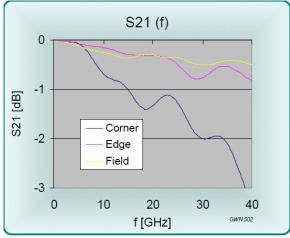


Figure 1: Insertion Loss, S21, E5544-B2

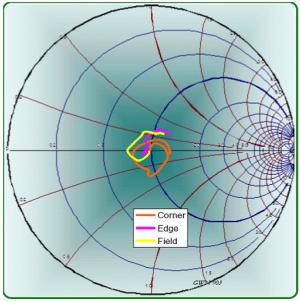


Figure 2: Measurement into 50Ω, E5544-B2

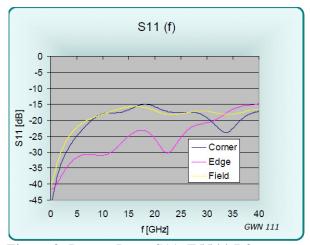


Figure 3: Return Loss, S11, E5544-B2

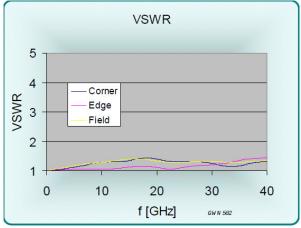


Figure 4: VSWR, E5544-B2



EQUIVALENT CIRCUITS / SPICE MODELS

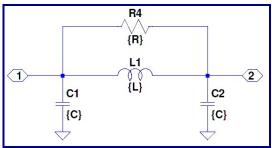


Figure 5: Pi Equivalent, Valid to >14 GHz

Site	e		R4
Corner	0.310 pF	0.94 nH	1000 Ω
Edge	0.329 pF	0.82 nH	1600 Ω
Field	0.362 pF	0.70 nH	1200 Ω
Diagonal	0.362 pF	0.70 nH	1200 Ω

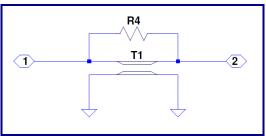


Figure 6: Transmission Line Model Valid to >40GHz

Site	Zo	L	R4	
Corner	55.2 Ω	17.11 ps	Ω 008	
Edge	50.0 Ω	16.43 ps	3000Ω	
Field	43.9 Ω	15.87 ps	$5000~\Omega$	

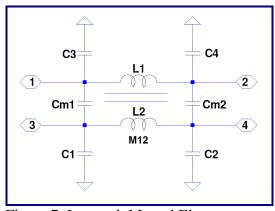


Figure 7: Lumped, Mutual Elements

	Coupler Zo K Elec Len Freq	
1		2
	3	

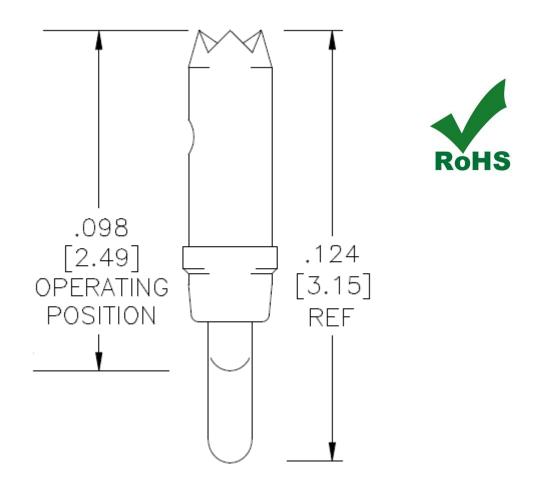
Figure 8: Transmission Line Equivalent for Crosstalk

Site	C1,2,3,4	Cm1,Cm2	L1,L2	М
Corner	0.155	0.036 pF	0.94	0.250 nH
Edge	0.164	0.034 pF	0.82	0.184 nH
Field	0.181	0.030 pF	0.70	0.126 nH
Diagonal	0.181	0.007 pF	0.70	0.057 nH

Z0	43.8	Ohms
Lel	15.5	ps
k	0.18	
f	31.5	Ghz



	E Series 1.0mm (.0394) pitch								
Probe Series	Initial Length inch/mm			Operating Operating		Self	Insertion Loss	Typical Contact	Maximum
Selles			inch/mm		Spring Force	Inductance	< -1db to	Resistance	Current
<u>E5566</u>	.121"	3.08	.098"	2.49	24-35 g	0.49 nH	>40 GHz	20 mOhms	4.3 A
<u>E5533</u>	.144"	3.66	.119"	3.02	25-40 g	0.72 nH	25.3 GHz	20 mOhms	8.5 A
E5544	.124"	3.15	.098"	2.49	30 g	0.70 nH	>40 GHz	30 mOhms	2.7 A
E5548	400"		4.5.00		20-39 g	1.04 nH	14.5 GHz	25 mOhms	7.0 A
<u>E5593</u>	.180"	4.57	.156"	3.96	27 g	1.14 nH	31.5 GHz	20 mOhms	6.0 A
E5656					28-36 g	0.90 nH	13.9 GHz	20 mOhms	6.0 A



Signal Integrity, Inc.

104 County Street, Ste. 210, Attleboro, MA 02703

Tel: 1-508-226-6480 Email: sales@signalin.com Internet: www.signalin.com

Signal Integrity makes no representation that the use of its products described herein, or the use of other technical information contained herein, will not infringe on existing or future patent rights. The descriptions contained herein do not imply the granting of licenses to make, use, or sell equipment constructed in accordance therewith. Specifications are subject to change without notice.